

**VCRRP-Channel Enhancement Mode Power MOSFET**

**Description**

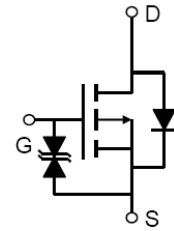
The VCRR15P25JK uses advanced trench technology and design to provide excellent  $R_{DS(ON)}$  with low gate charge. It can be used in a wide variety of applications.

**General Features**

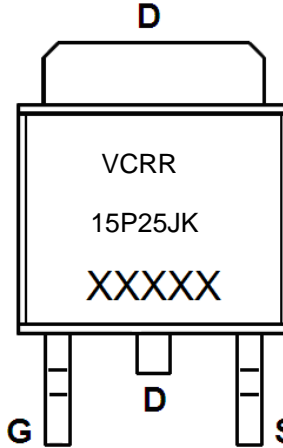
- $V_{DS} = -150V, I_D = -25A$
- $R_{DS(ON)} < 150m\Omega @ V_{GS} = -10V$  (Typ.=120mR)
- $R_{DS(ON)} < 160m\Omega @ V_{GS} = -4.5V$  (Typ.=131mR)
- Super high dense cell design
- Advanced trench process technology
- Reliable and rugged
- High density cell design for ultra low On-Resistance

**Application**

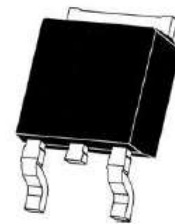
- Portable equipment and battery powered systems



Schematic diagram



Marking and pin assignment



TO-252-2L top view

**Package Marking and Ordering Information**

Device Marking	Device	Device Package	Reel Size	Tape width	Quantity
VCRR15P25JK	VCRR15P25JK	TO-252-2L	Ø330mm	12mm	2500 units

**Absolute Maximum Ratings ( $T_C=25^\circ C$  unless otherwise noted)**

Parameter	Symbol	Limit	Unit
Drain-Source Voltage	$V_{DS}$	-145	V
Gate-Source Voltage	$V_{GS}$	$\pm 20$	V
Drain Current-Continuous	$I_D$	-25	A
Drain Current-Continuous( $T_C=100^\circ C$ )	$I_D(100^\circ C)$	-17	A
Pulsed Drain Current	$I_{DM}$	-140	A
Maximum Power Dissipation	$P_D$	160	W
Derating factor		1.3	W/ $^\circ C$
Operating Junction and Storage Temperature Range	$T_J, T_{STG}$	-55 To 150	$^\circ C$

## Thermal Characteristic

Thermal Resistance, Junction-to-Case <sup>(Note 2)</sup>	$R_{\theta Jc}$	0.8	$^{\circ}C/W$
Thermal Resistance, Junction-to-Ambient <sup>(Note 2)</sup>	$R_{\theta JA}$	40	$^{\circ}C/W$

## Electrical Characteristics ( $T_C=25^{\circ}C$ unless otherwise noted)

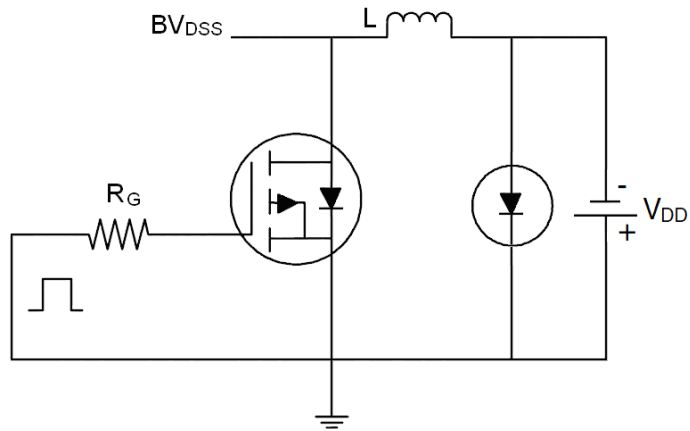
Parameter	Symbol	Condition	Min	Typ	Max	Unit
<b>Off Characteristics</b>						
Drain-Source Breakdown Voltage	$BV_{DSS}$	$V_{GS}=0V, I_D=-250\mu A$	-145	-155	-	V
Zero Gate Voltage Drain Current	$I_{DSS}$	$V_{DS}=-145V, V_{GS}=0V$	-	-	1	$\mu A$
Gate-Body Leakage Current	$I_{GSS}$	$V_{GS}=\pm 20V, V_{DS}=0V$	-	-	$\pm 10$	$\mu A$
<b>On Characteristics</b> <sup>(Note 3)</sup>						
Gate Threshold Voltage	$V_{GS(th)}$	$V_{DS}=V_{GS}, I_D=-250\mu A$	-1.5	-1.9	-3	V
Drain-Source On-State Resistance	$R_{DS(on)}$	$V_{GS}=-10V, I_D=-20A$	-	120	150	m $\Omega$
		$V_{GS}=-4.5V, I_D=-20A$	-	131	160	
Forward Transconductance	$g_{FS}$	$V_{DS}=-5V, I_D=-20A$	5	-	-	S
<b>Dynamic Characteristics</b> <sup>(Note 4)</sup>						
Input Capacitance	$C_{iss}$	$V_{DS}=-75V, V_{GS}=0V,$ $F=1.0MHz$	-	7650	-	pF
Output Capacitance	$C_{oss}$		-	148	-	pF
Reverse Transfer Capacitance	$C_{rss}$		-	131	-	pF
<b>Switching Characteristics</b> <sup>(Note 4)</sup>						
Turn-on Delay Time	$t_{d(on)}$	$V_{DD}=-75V, I_D=-20A$ $V_{GS}=-10V, R_{GEN}=9.1\Omega$	-	17	-	nS
Turn-on Rise Time	$t_r$		-	80	-	nS
Turn-Off Delay Time	$t_{d(off)}$		-	45	-	nS
Turn-Off Fall Time	$t_f$		-	65	-	nS
Total Gate Charge	$Q_g$	$V_{DS}=-75V, I_D=-20A,$ $V_{GS}=-10V$	-	137	-	nC
Gate-Source Charge	$Q_{gs}$		-	25	-	nC
Gate-Drain Charge	$Q_{gd}$		-	28	-	nC
<b>Drain-Source Diode Characteristics</b>						
Diode Forward Voltage <sup>(Note 3)</sup>	$V_{SD}$	$V_{GS}=0V, I_S=-25A$	-	-	-1.2	V
Diode Forward Current <sup>(Note 2)</sup>	$I_S$	-	-	-	-25	A
Reverse Recovery Time	$t_{rr}$	$T_J=25^{\circ}C, I_F=-25A$ $di/dt=100A/\mu s$ <sup>(Note 3)</sup>	-	90	-	nS
Reverse Recovery Charge	$Q_{rr}$		-	105	-	nC

## Notes:

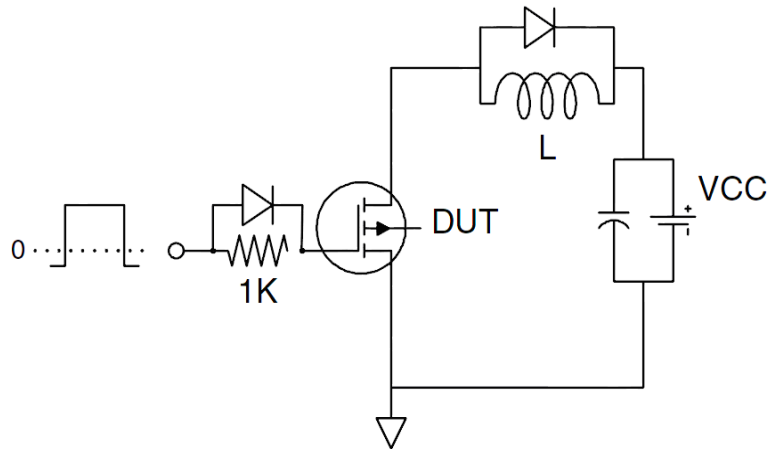
1. Repetitive Rating: Pulse width limited by maximum junction temperature.
2. The value of  $R_{\theta JA}$  is measured with the device mounted on 1in2 FR-4 board with 2oz. Copper, in a still air environment with  $T_A=25^{\circ}C$ . The maximum allowed junction temperature of  $150^{\circ}C$
3. Pulse Test: Pulse Width  $\leq 300\mu s$ , Duty Cycle  $\leq 2\%$ .
4. Guaranteed by design, not subject to production
5. EAS condition:  $T_J=25^{\circ}C, V_{DB}=-75V, V_G=-10V, L=0.5mH, R_g=25\Omega$

**Test Circuit**

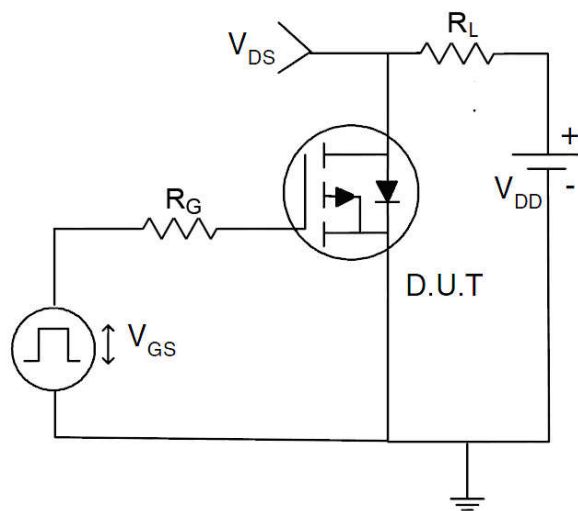
**1) E<sub>AS</sub> Test Circuit**



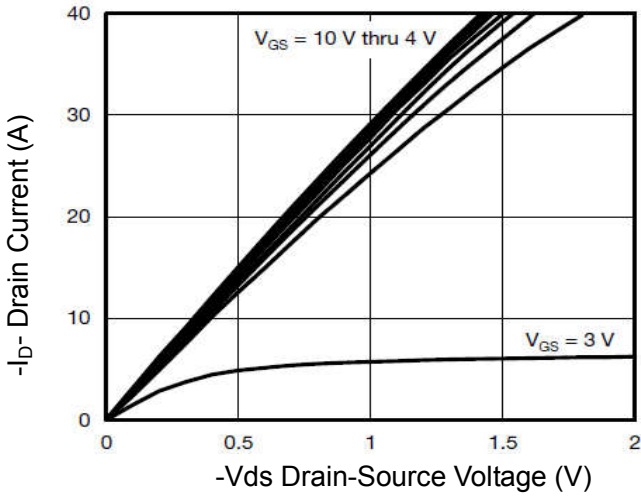
**2) Gate Charge Test Circuit**



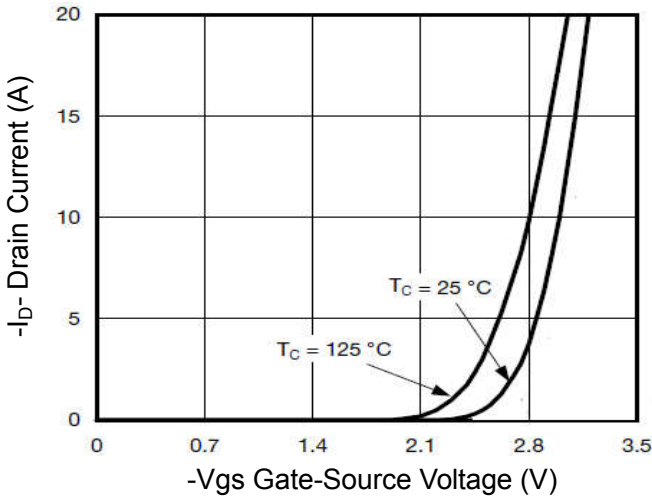
**3) Switch Time Test Circuit**



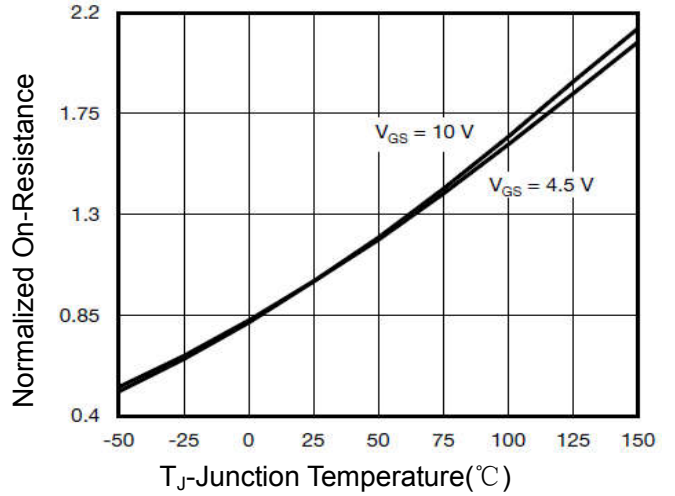
**Typical Electrical and Thermal Characteristics (Curves)**



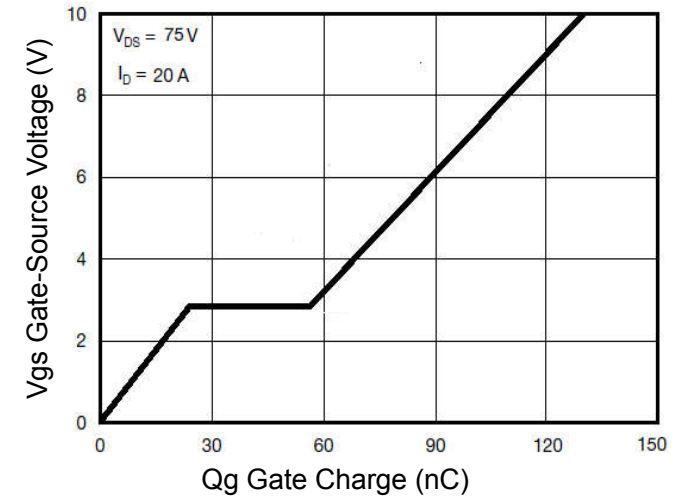
**Figure 1 Output Characteristics**



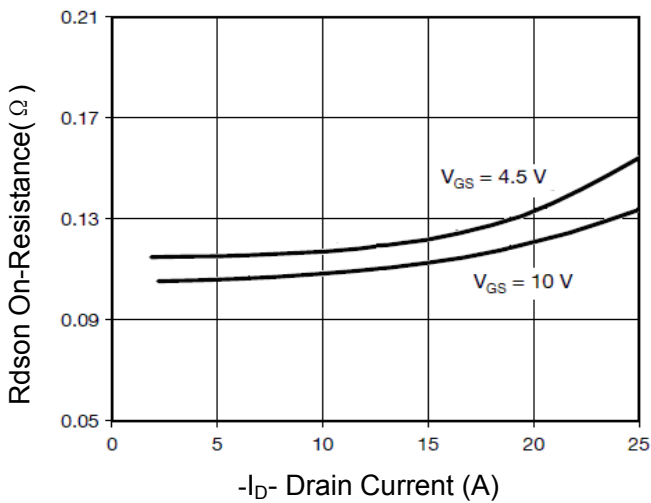
**Figure 2 Transfer Characteristics**



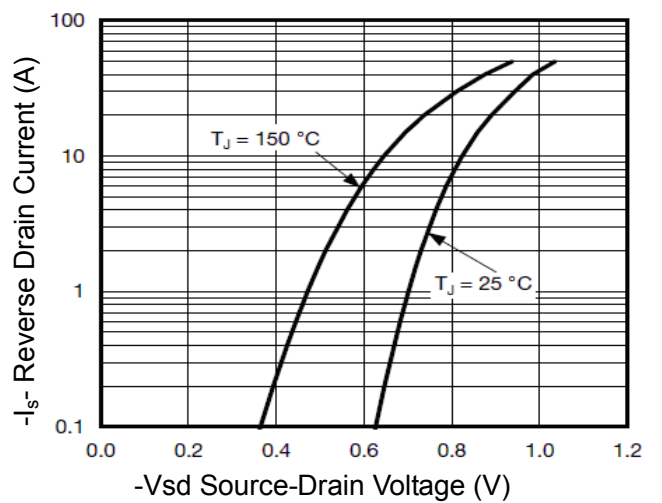
**Figure 4 Rdson-Junction Temperature**



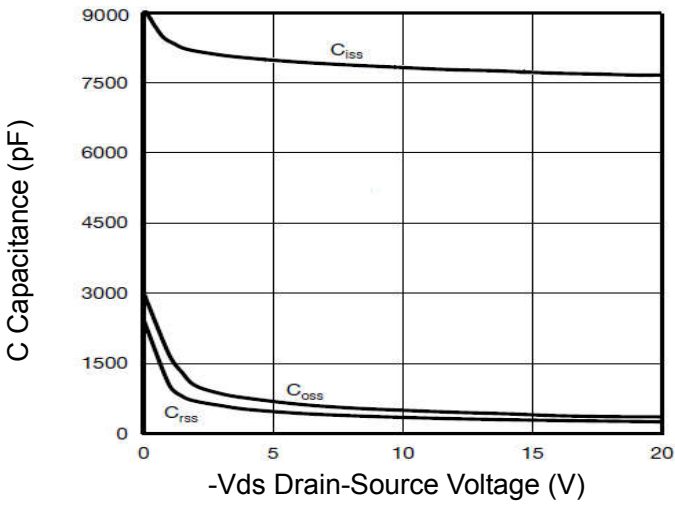
**Figure 5 Gate Charge**



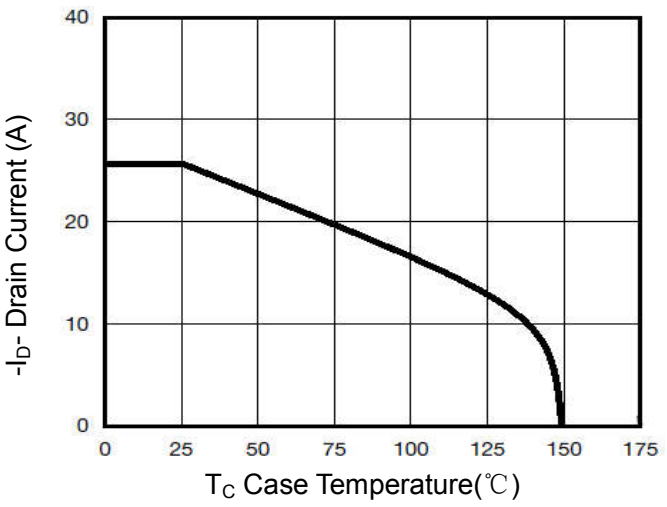
**Figure 3 Rdson- Drain Current**



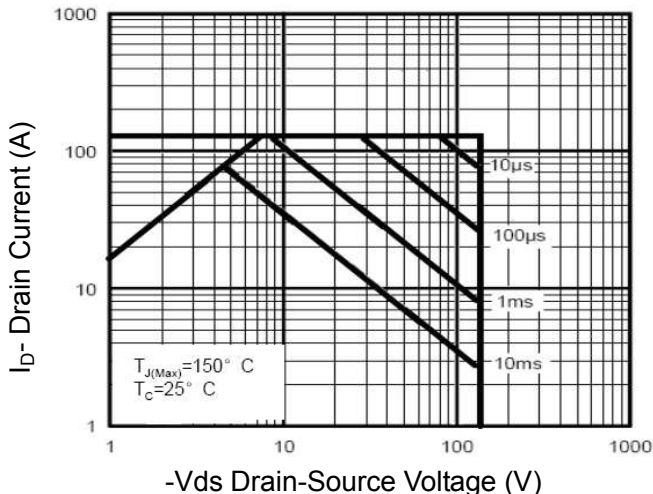
**Figure 6 Source- Drain Diode Forward**



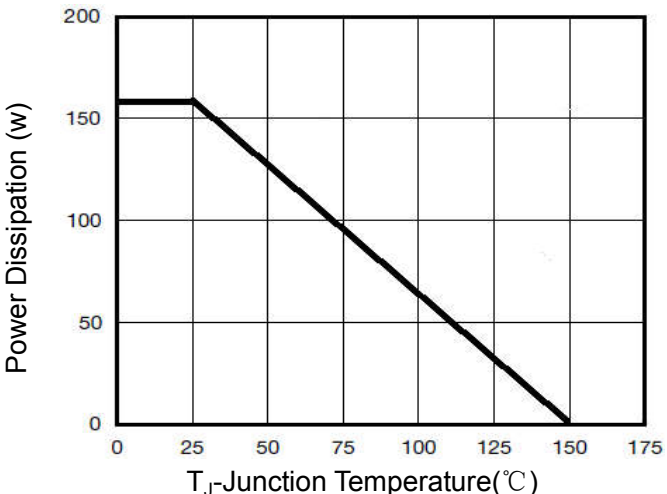
**Figure 7 Capacitance vs Vds**



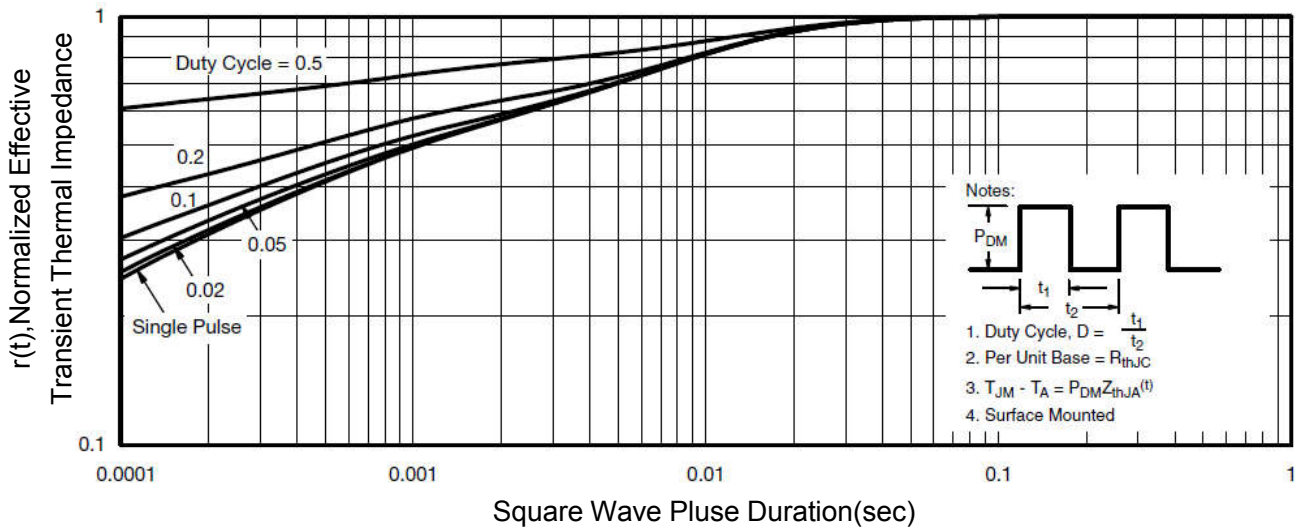
**Figure 9 Drain Current vs Case Temperature**



**Figure 8 Safe Operation Area**

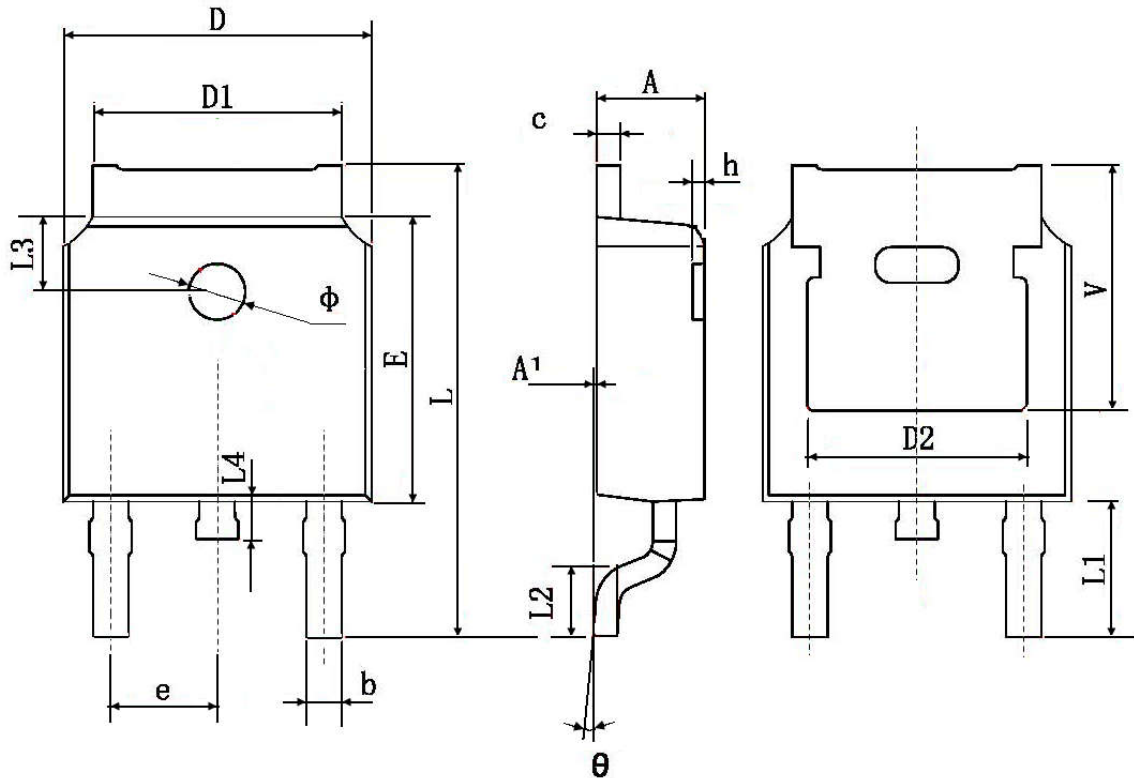


**Figure 10 Power De-rating**



**Figure 11 Normalized Maximum Transient Thermal Impedance**

## TO-252 Package Information



Symbol	Dimensions In Millimeters		Dimensions In Inches	
	Min.	Max.	Min.	Max.
A	2.200	2.400	0.087	0.094
A1	0.000	0.127	0.000	0.005
b	0.660	0.860	0.026	0.034
c	0.460	0.580	0.018	0.023
D	6.500	6.700	0.256	0.264
D1	5.100	5.460	0.201	0.215
D2	4.83 TYP.		0.190 TYP.	
E	6.000	6.200	0.236	0.244
e	2.186	2.386	0.086	0.094
L	9.800	10.400	0.386	0.409
L1	2.900 TYP.		0.114 TYP.	
L2	1.400	1.700	0.055	0.067
L3	1.600 TYP.		0.063 TYP.	
L4	0.600	1.000	0.024	0.039
Φ	1.100	1.300	0.043	0.051
θ	0°	8°	0°	8°
h	0.000	0.300	0.000	0.012
V	5.350 TYP.		0.211 TYP.	

## Attention

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